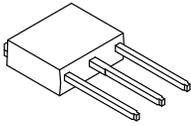


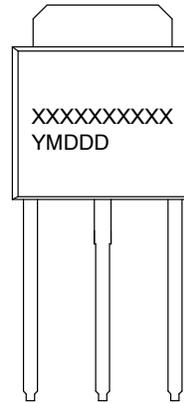
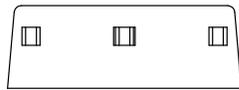
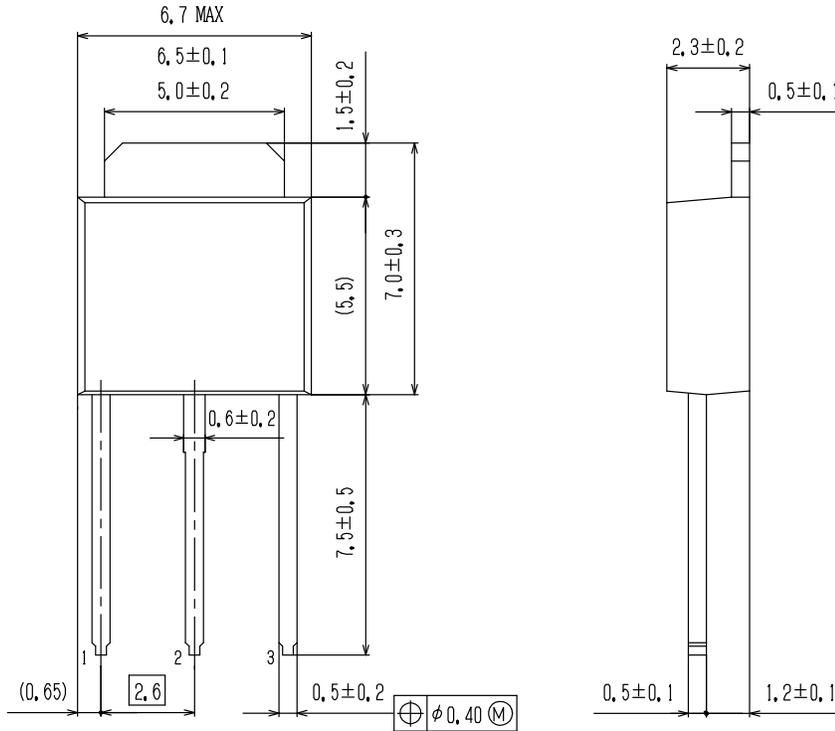
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



IPAK / TP3H
CASE 369AF
ISSUE A

DATE 24 OCT 2013

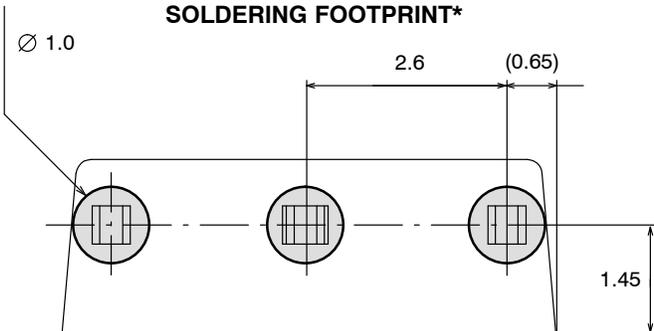


GENERIC MARKING DIAGRAM*

XXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

(Unit: mm)

Package name
TP3H

○ Through Hole Area

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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